



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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MG12150S-BN2MM



Features

- High short circuit capability, self limiting short circuit current
- IGBT³ CHIP(Trench+Field Stop technology)
- $V_{CE(sat)}$ with positive temperature coefficient
- Fast switching and short tail current
- Free wheeling diodes with fast and soft reverse recovery
- Low switching losses

Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E71639

Applications

- High frequency switching application
- Medical applications
- Motion/servo control
- UPS systems

Module Characteristics ($T_c = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Unit
$T_J \text{ max}$	Max. Junction Temperature				150	$^\circ\text{C}$
$T_{J \text{ op}}$	Operating Temperature		-40		125	$^\circ\text{C}$
T_{stg}	Storage Temperature		-40		125	$^\circ\text{C}$
V_{isol}	Insulation Test Voltage	AC, t=1min		3000		V
CTI	Comparative Tracking Index		350			
Torque	Module-to-Sink	Recommended (M6)	3		5	N·m
Torque	Module Electrodes	Recommended (M5)	2.5		5	N·m
Weight				160		g

Absolute Maximum Ratings ($T_c = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameters	Test Conditions	Values	Unit
IGBT				
V_{CES}	Collector - Emitter Voltage	$T_J=25^\circ\text{C}$	1200	V
V_{GES}	Gate - Emitter Voltage		± 20	V
I_C	DC Collector Current	$T_c=25^\circ\text{C}$	200	A
		$T_c=80^\circ\text{C}$	150	A
I_{CM}	Repetitive Peak Collector Current	$t_p=1\text{ms}$	300	A
P_{tot}	Power Dissipation Per IGBT		625	W
Diode				
V_{RRM}	Repetitive Reverse Voltage	$T_J=25^\circ\text{C}$	1200	V
$I_{\text{F(AV)}}$	Average Forward Current	$T_c=25^\circ\text{C}$	200	A
		$T_c=80^\circ\text{C}$	150	A
I_{FRM}	Repetitive Peak Forward Current	$t_p=1\text{ms}$	300	A
I^2t		$T_J=125^\circ\text{C}, t=10\text{ms}, V_R=0\text{V}$	4350	A^2s

Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

Electrical and Thermal Specifications ($T_c = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameters	Test Conditions	Min	Typ	Max	Unit
IGBT						
$V_{GE(th)}$	Gate - Emitter Threshold Voltage	$V_{CE}=V_{GE}, I_C=6\text{mA}$	5.0	5.8	6.5	V
$V_{CE(sat)}$	Collector - Emitter Saturation Voltage	$I_C=150\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$		1.7		V
		$I_C=150\text{A}, V_{GE}=15\text{V}, T_J=125^\circ\text{C}$		1.9		V
I_{CES}	Collector Leakage Current	$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$			1	mA
		$V_{CE}=1200\text{V}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$			5	mA
I_{GES}	Gate Leakage Current	$V_{CE}=0\text{V}, V_{GE}=\pm 15\text{V}, T_J=125^\circ\text{C}$	-400		400	nA
R_{Gint}	Integrated Gate Resistor			5		Ω
Q_{ge}	Gate Charge	$V_{CC}=600\text{V}, I_C=150\text{A}, V_{GE}=\pm 15\text{V}$		1.4		μC
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		10.5		nF
C_{res}	Reverse Transfer Capacitance				0.4	
$t_{d(on)}$	Turn - on Delay Time	$V_{CC}=600\text{V}$ $I_C=150\text{A}$ $R_G=2.4\Omega$ $V_{GE}=\pm 15\text{V}$ Inductive Load	$T_J=25^\circ\text{C}$		260	ns
			$T_J=125^\circ\text{C}$		290	ns
t_r	Rise Time		$T_J=25^\circ\text{C}$		30	ns
			$T_J=125^\circ\text{C}$		50	ns
$t_{d(off)}$	Turn - off Delay Time		$T_J=25^\circ\text{C}$		420	ns
			$T_J=125^\circ\text{C}$		520	ns
t_f	Fall Time		$T_J=25^\circ\text{C}$		70	ns
			$T_J=125^\circ\text{C}$		90	ns
E_{on}	Turn - on Energy		$T_J=25^\circ\text{C}$		12	mJ
			$T_J=125^\circ\text{C}$		16	mJ
E_{off}	Turn - off Energy	$T_J=25^\circ\text{C}$		11	mJ	
		$T_J=125^\circ\text{C}$		14.5	mJ	
I_{SC}	Short Circuit Current	$t_{psc}\leq 10\mu\text{s}, V_{GE}=15\text{V}; T_J=125^\circ\text{C}, V_{CC}=900\text{V}$		600		A
R_{thJC}	Junction-to-Case Thermal Resistance (Per IGBT)				0.2	K/W
Diode						
V_F	Forward Voltage	$I_F=150\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$		1.65		V
		$I_F=150\text{A}, V_{GE}=0\text{V}, T_J=125^\circ\text{C}$		1.65		V
I_{RRM}	Max. Reverse Recovery Current	$I_F=150\text{A}, V_R=600\text{V}$ $di_f/dt=-4000\text{A}/\mu\text{s}$ $T_J=125^\circ\text{C}$		210		A
Q_{rr}	Reverse Recovery Charge			30.0		μC
E_{rec}	Reverse Recovery Energy			13		mJ
R_{thJCD}	Junction-to-Case Thermal Resistance (Per Diode)				0.36	K/W

Figure 1: Typical Output Characteristics

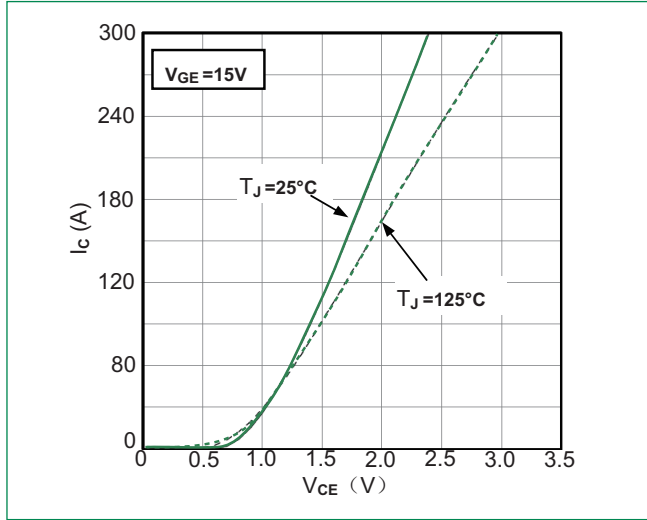


Figure 2: Typical Output characteristics

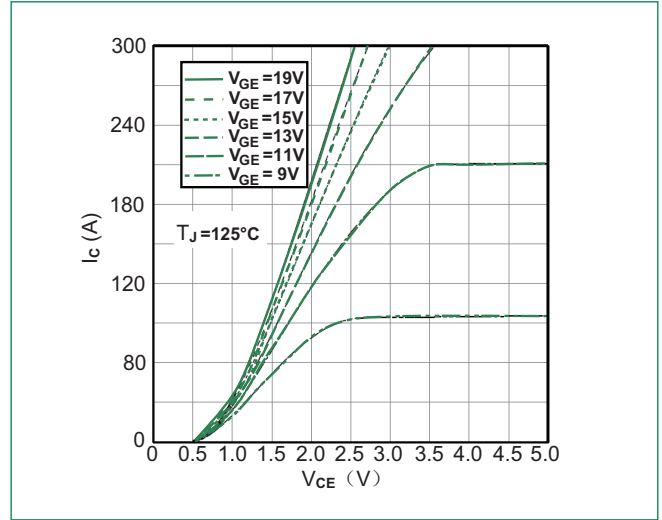


Figure 3: Typical Transfer characteristics

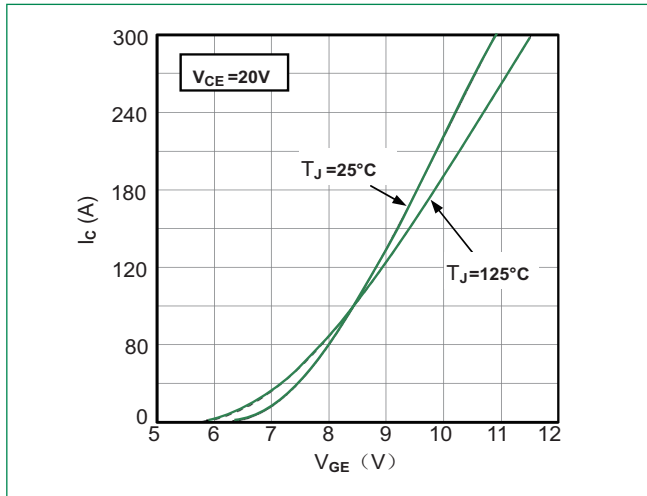


Figure 4: Switching Energy vs. Gate Resistor

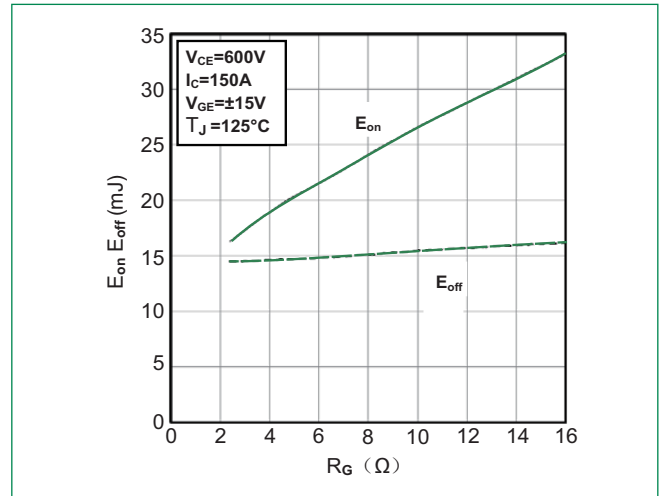


Figure 5: Switching Energy vs. Collector Current

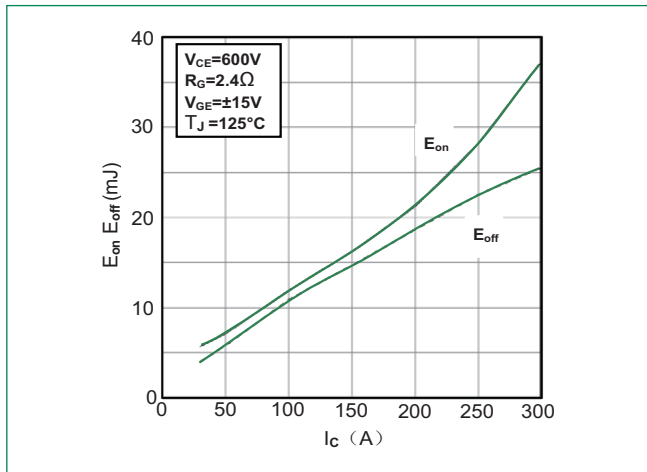


Figure 6: Reverse Biased Safe Operating Area

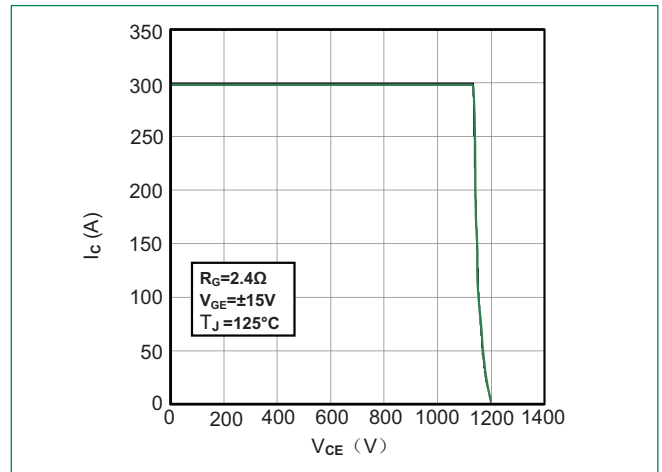


Figure 7: Diode Forward Characteristics

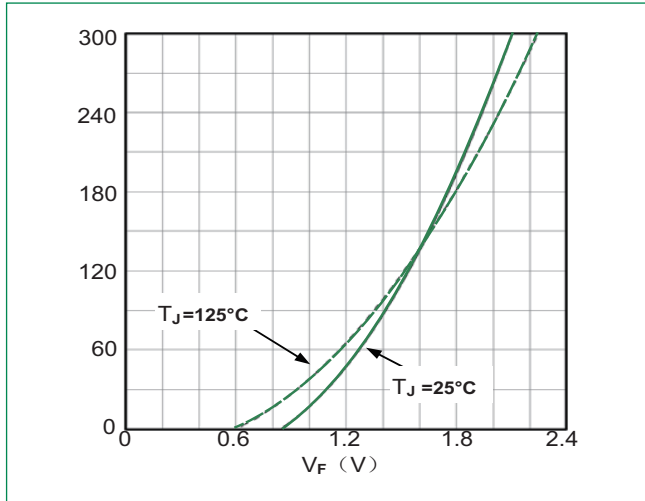


Figure 8: Switching Energy vs. Gate Resistor

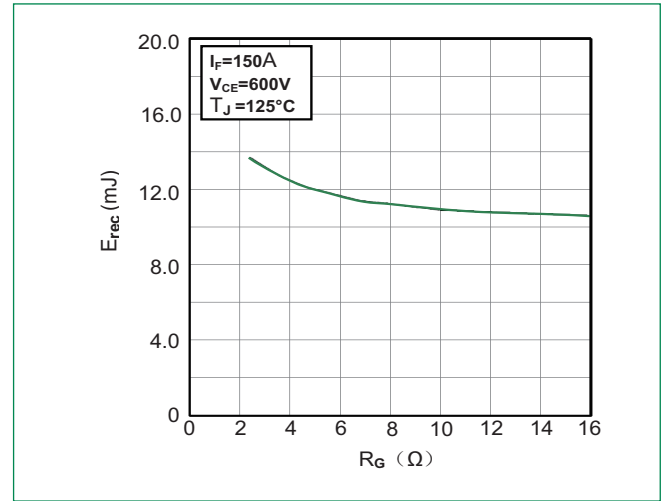


Figure 9: Switching Energy vs. Forward Current

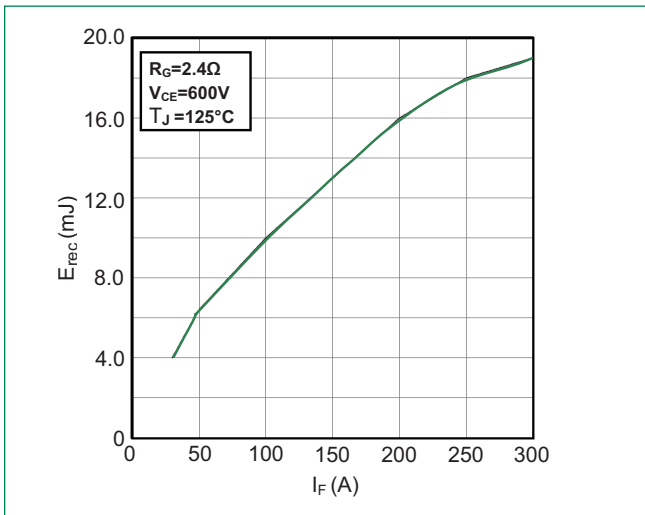
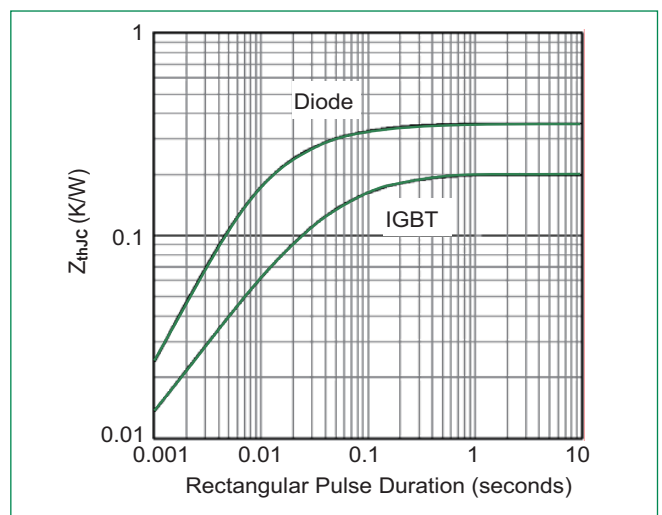
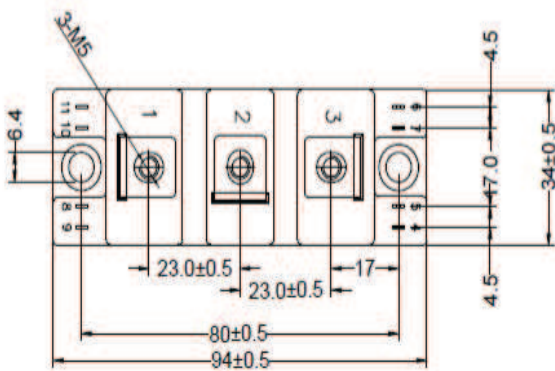
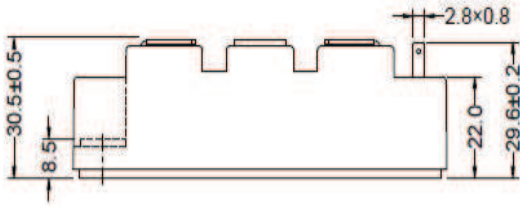


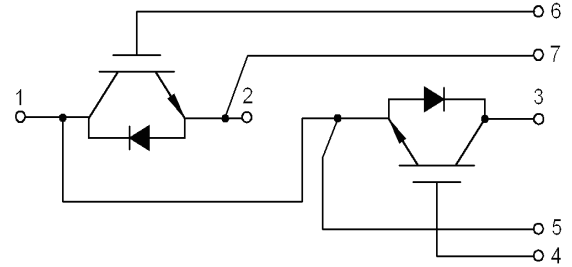
Figure 10: Transient Thermal Impedance



Dimensions-Package S



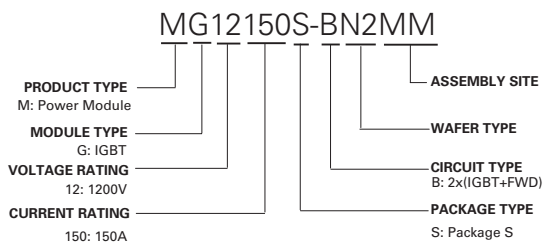
Circuit Diagram



Packing Options

Part Number	Marking	Weight	Packing Mode	M.O.Q
MG12150S-BN2MM	MG12150S-BN2MM	160g	Bulk Pack	100

Part Numbering System



Part Marking System

